

WSK060

蓝宝石切割机床

WSK060 Sapphire Cutting Machine



主要性能参数

行程 Stroke	5000mm
长度 Length	2000mm
厚度 Thickness	>0.2mm

主要参数 Main parameters

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheel base	440mm
导轮长度 Guide wheel length	355mm
导轮间距 Guide wheel spacing	300mm (center-to-center)
进给速度 Feeding rate	0.01mm/200mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	前开或后开切割/双向切割 Forward or reverse cutting/two-way cutting
存储空间 Storage space	300mm
冷却方式 Cooling method	水冷 Water cooling

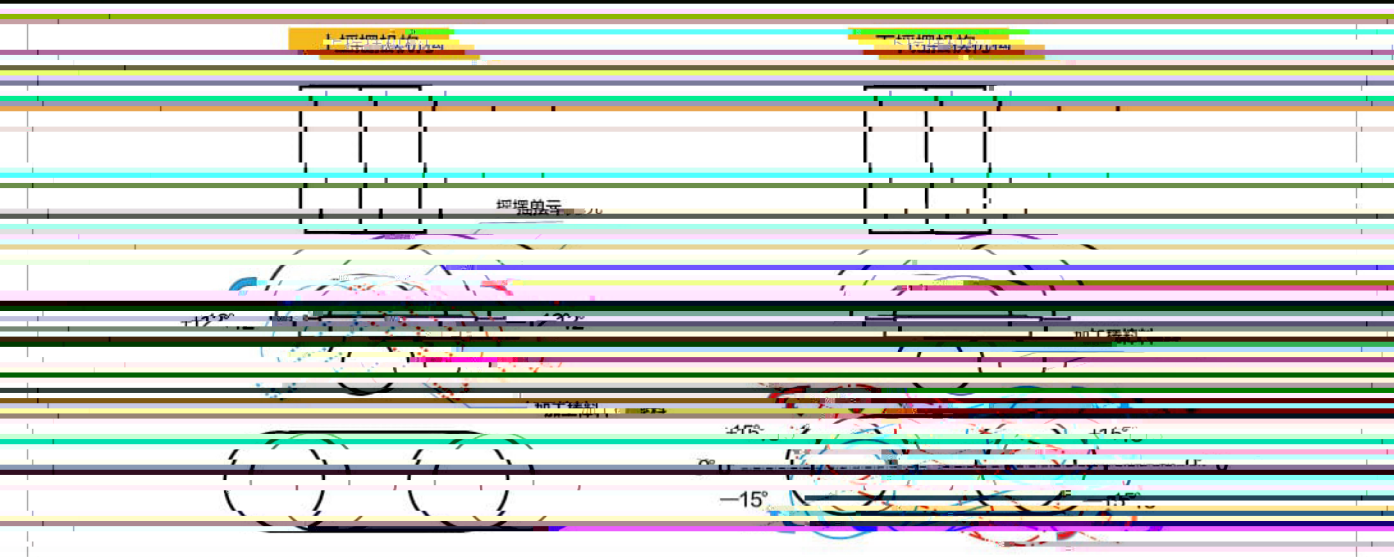
能源消耗 Energy consumption

电功率 Power	22kW/380V, 50Hz, 3-phase
冷却功率 Cooling power	35kW
冷却水压 Cooling water pressure	1.2~1.7MPa

外形尺寸 Overall dimensions

机床外形尺寸 (不含机械手) Equipment size (without robot)	4600mm×2450mm×2550mm
机床重量 Weight	12000kg

示意图 Schematic



设备用途与性能特点

- 本机适用于切割硅片、砷化镓、蓝宝石、碳化硅、氮化镓、蓝宝石衬底等。
- 机床所有电器元件均采用国际知名品牌，保证机床的稳定性。
- 采用先进的切割技术，切割效率高。
- 电控柜配备温度控制装置，确保切割精度。
- 设备具备摇摆功能，可适应不同厚度的切割需求，缩短了切割时间，并提高了晶片的品质。
- 滑轮数量最少化设计（仅6个滑轮），减少切割时的摩擦阻力。

- The machine is suitable for cutting silicon wafers, gallium arsenide, sapphire crystals, etc.
- All electrical components are of international brands to ensure the stability of the machine.
- Apply integrated PC of SIEMENS controller, ensuring accuracy and efficiency.
- The electric control cabinet is equipped with temperature control device to ensure the accuracy of the cutting process.
- The equipment has a swinging function, which can adapt to different thickness cutting requirements, shorten the cutting time, and improve the quality of the crystal.
- Minimal design number of pulleys (only 6 pulleys) to reduce friction and fatigue.